



# Sputter Series

## Uni-body Design Concept

Foot-print outstanding (ref 1.0m\*1.7m)

## Creative Magnetron Design

Magnetron target structure self-designed creatively, designed and modified base on customer depending

## Flexible Target Configuration

Magnetron target face-down or face-up optional, also angle tiltable and deposition distance tunable

## Advanced Electrode Control

Electrode rotational, and temperature controllable suitable for different process application

## RF Bias Capability

Substrate can be RF biased for in-situ clean, also better process tuned and controlled

## Cost or Performance Orientation

RF, Pump, Values etc. depending on requirements

## Sample Handling Options

Open-Load or Load-Lock



Specification	Parameters
Wafer Size Range	4,6,8,12 inch or multi-wafers optional
Magnetron Sputtering Source	2-6 optional
Substrate Temperature	Water-cooling, 400°C, 800°C, 1200°C, optional
Gas System	2 lines (Standard), numbers of line customized
Power	DC or RF customized, automatic switcher
Non-Uniformity	Less than $\pm 5\%$
Pre-Cleaning	Independent chamber or in-situ, RF plasma, optional
Base Pressure	Better than $5E-7$ Torr, higher vacuum customized